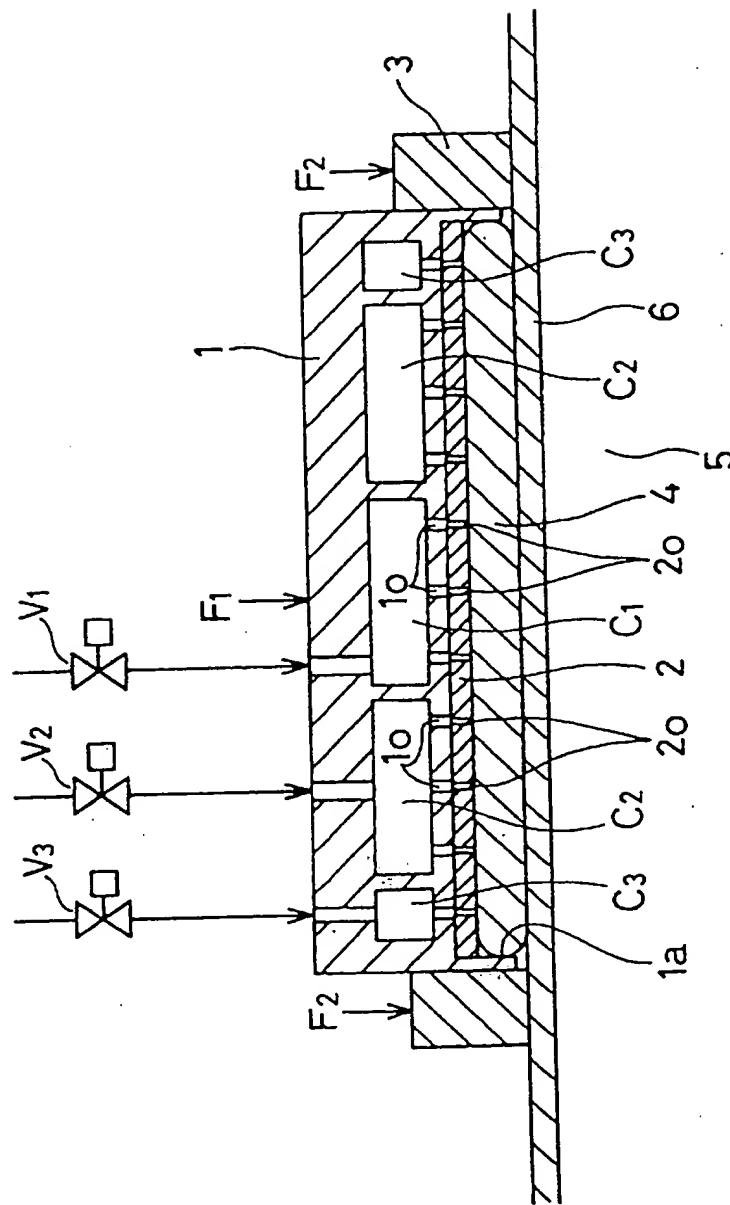


F / G. 1



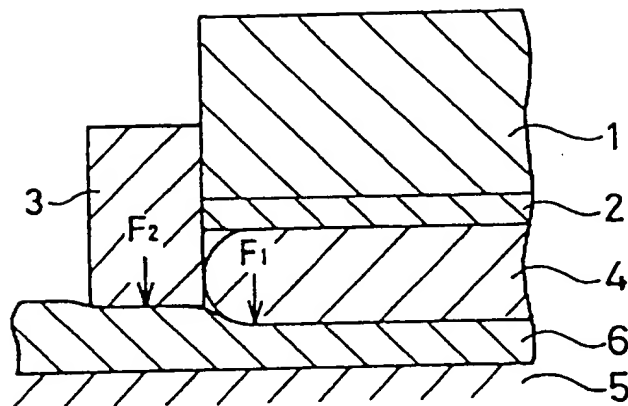
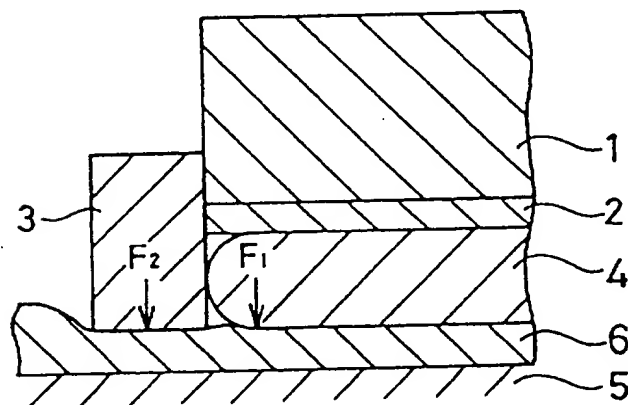
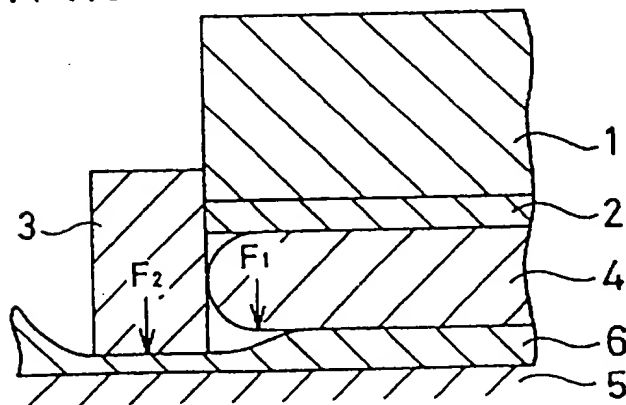
$$F_1 > F_2$$

$$F_1 \approx F_2$$

$$F_1 < F_2$$


FIG. 3A

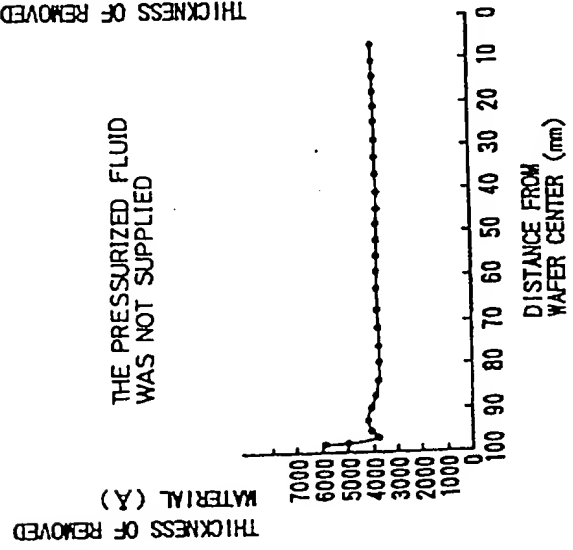


FIG. 3B

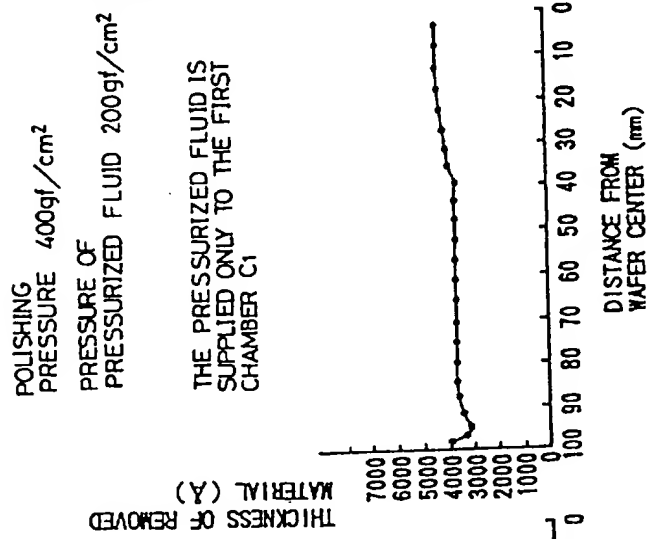
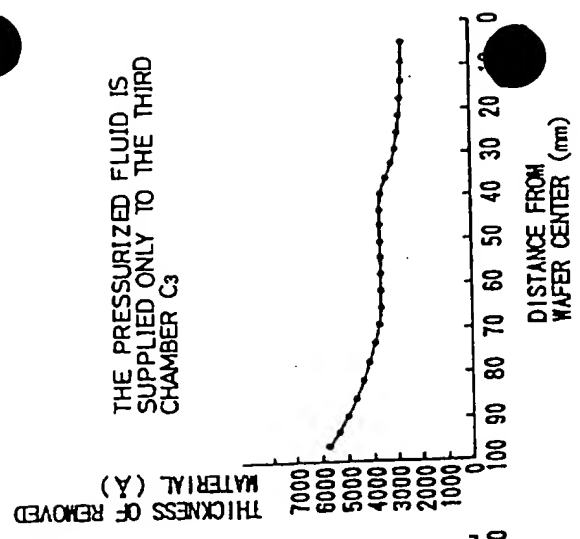


FIG. 3C



000000" 8866560

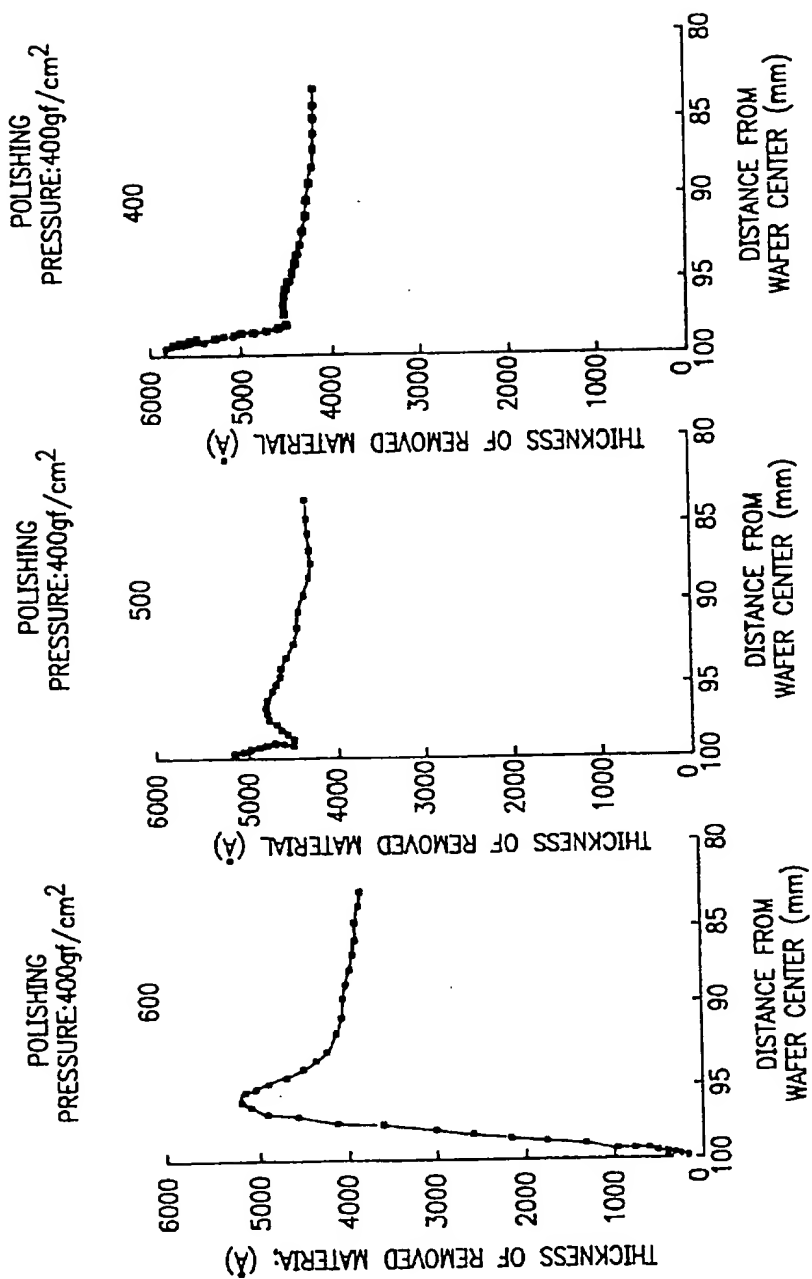


FIG. 4C

FIG. 4B

FIG. 4A

The figure contains two graphs, (A) and (B), showing the thickness of removed material (in Å) as a function of the distance from the wafer center (in mm) for a polishing pressure of 400 gf/cm².

Graph (A): The y-axis is labeled "THICKNESS OF REMOVED MATERIAL (Å)" and ranges from 0 to 6000. The x-axis is labeled "DISTANCE FROM WAFER CENTER (mm)" and ranges from 100 to 80. The curve shows a sharp increase in thickness starting around 95 mm, reaching a peak of approximately 4500 Å at 85 mm, and then decreasing to about 3500 Å at 80 mm.

Graph (B): The y-axis is labeled "THICKNESS OF REMOVED MATERIAL (Å)" and ranges from 0 to 6000. The x-axis is labeled "DISTANCE FROM WAFER CENTER (mm)" and ranges from 100 to 80. The curve shows a sharp increase in thickness starting around 95 mm, reaching a peak of approximately 4500 Å at 85 mm, and then decreasing to about 3500 Å at 80 mm.

FIG. 4D

F/G.5

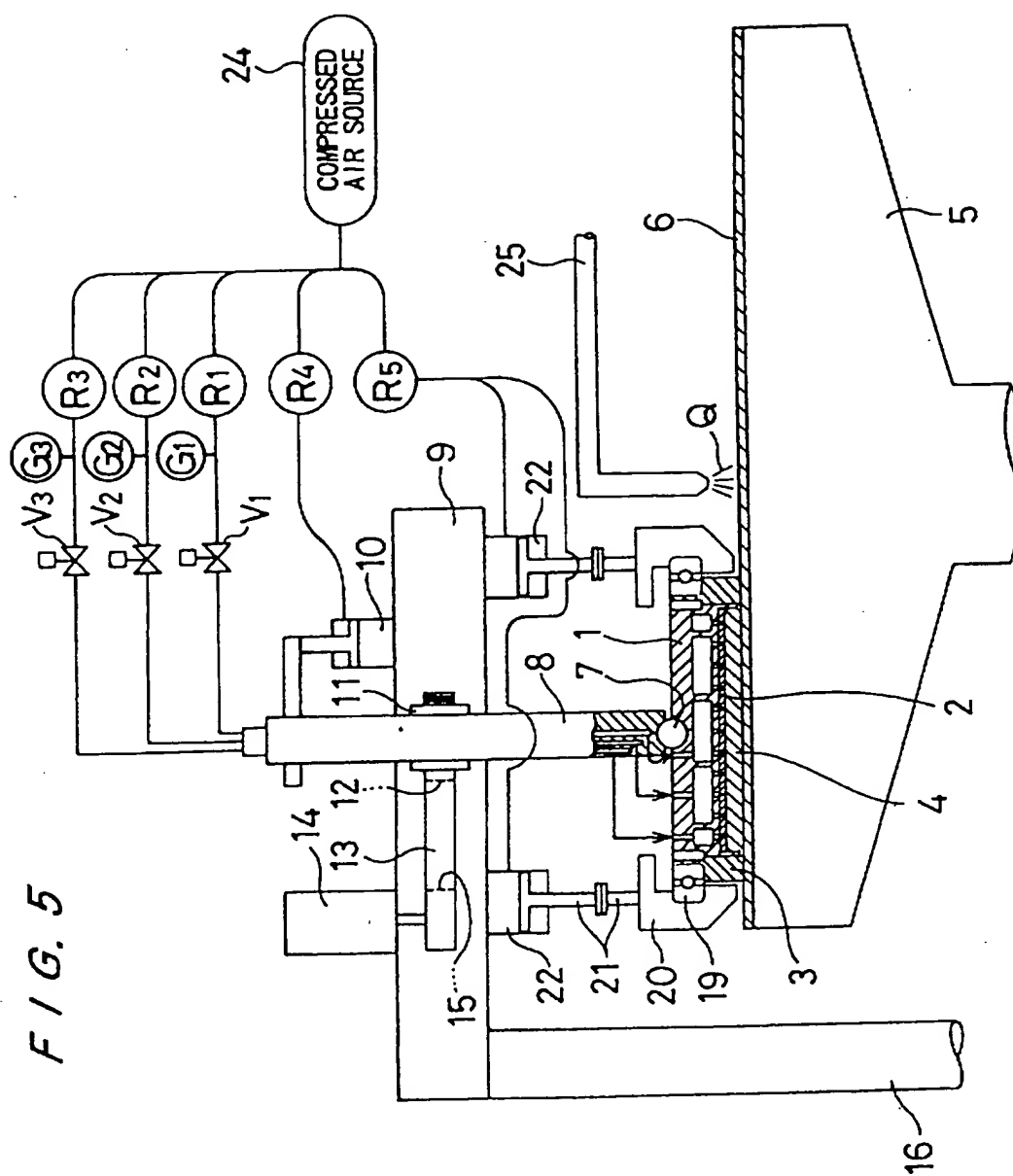
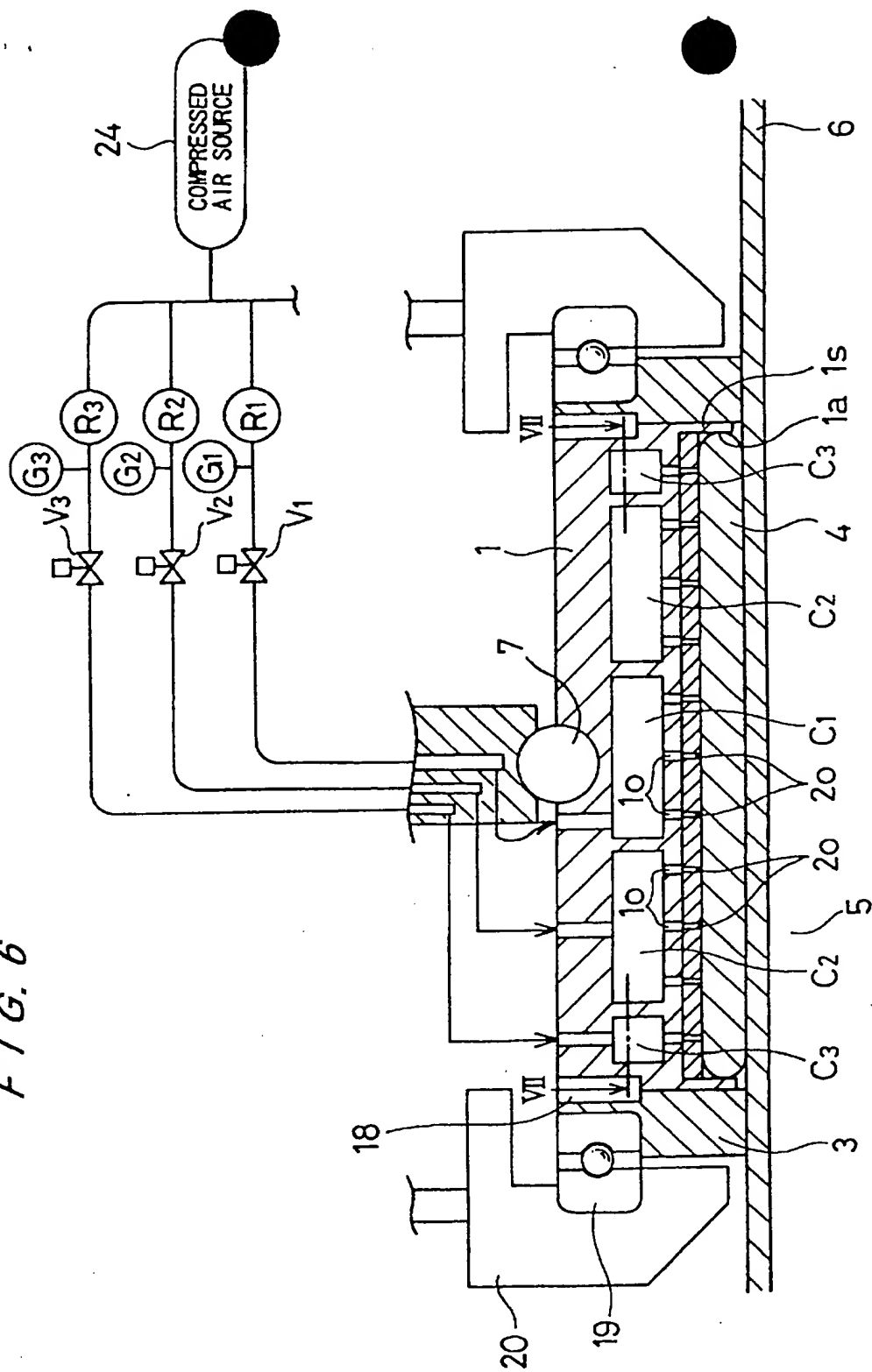
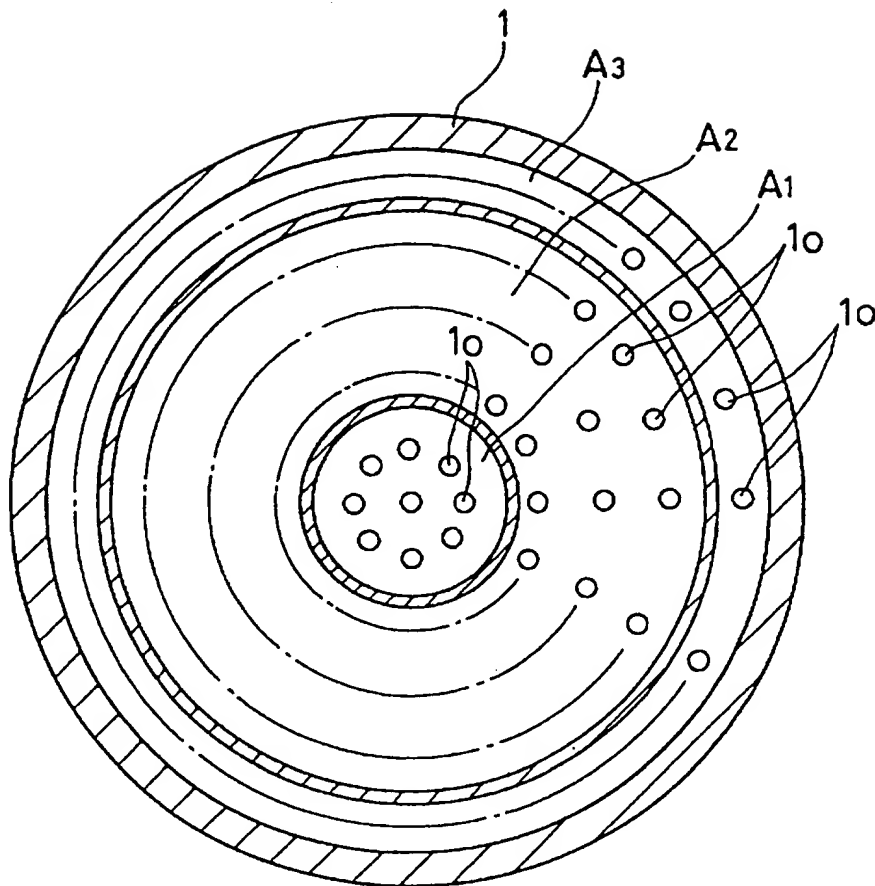


FIG. 6



[illegible]

F / G. 8

